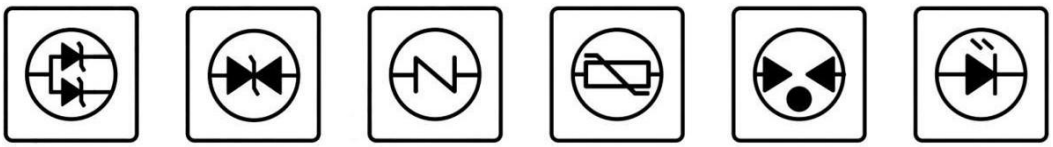
MSKSEMI 美森科
SEMICONDUCTOR



PESD1IVN24-LSYL-MS

Product specification

PESD1IVN24-LSYL-MS

Features

- IEC61000-4-2 (ESD) ±8kV (Contact)
- ±15kV (Air)
- IEC61000-4-4 (EFT) 40A (5/50ηs)
- IEC61000-4-5 (Lighting) 3A(8/20μs)
- 100 Watts Peak Pulse Power (tp=8/20μs)
- Working voltages : 24V
- Low clamping voltage
- Low leakage current

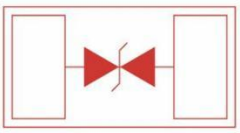
Applications

- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Projection TV
- Cellular handsets and accessories
- Portable instrumentation
- Peripherals

Mechanical Characteristics

- DFN1006 package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel
- Reel size: 7 inch

Reference News

PACKAGE OUTLINE	Circuit Diagram	Marking
 DFN1006		DH

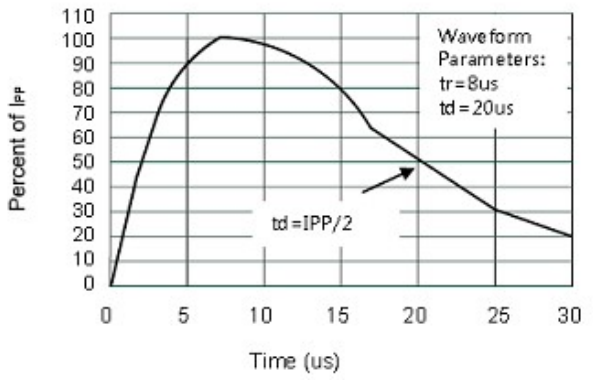
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±8 ±15	kV
P_{PP}	Peak Pulse Power (8/20μs)	150	W
T_{OPT}	Operating Temperature	-55 ~ +125	℃
T_{STG}	Storage Temperature	-55 ~ +150	℃
T_L	Lead Soldering Temperature	260 (10 sec.)	℃

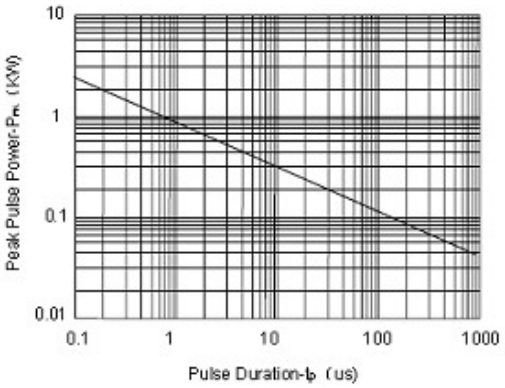
ELECTRICAL CHARACTERISTICS (Tamb=25℃)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	I_T = 1mA	26		32	V
I_R	Reverse Leakage Current	V_{RWM} = 24V			1	μA
V_{C1}	Clamping Voltage 1	I_{PP} = 1A, t_p = 8/20μs			40	V
V_{C2}	Clamping Voltage 2	I_{PP} = 3A, t_p = 8/20μs			50	V
C_J	Junction Capacitance	V_R = 0V, f = 1MHz		8	15	pF

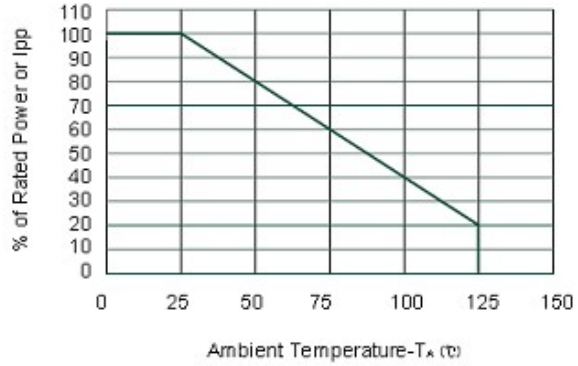
ELECTRICAL CHARACTERISTICS CURVE



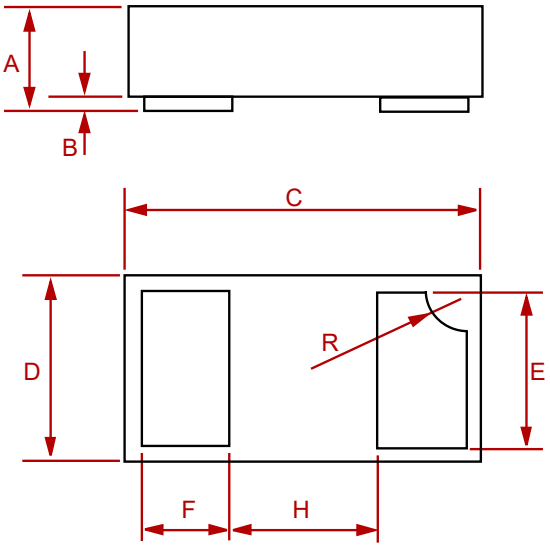
Pulse Waveform



Non-Repetitive Peak Pulse Power vs. Pulse Time

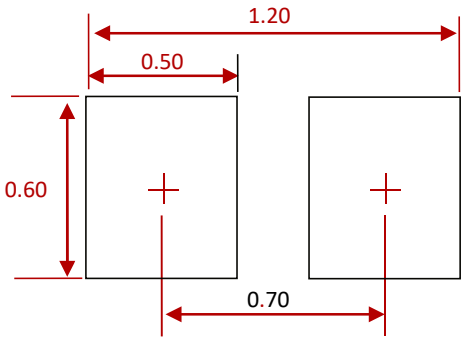


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
PESD1IVN24-LSYL-MS	DF1006	10000

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